

FLH Ref. No.: 450100-02916

101686272

PA		U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
To the Honorable Commissioner of Patents and Trace an	ks Please record the attached original do	cuments or copy thereof.
1. Name of conveying party(ies)	2. Name and address of receiving	party(ies)
Junichi YAMASHITA, Hiroaki OGAWA, Hitoshi HONDA, Helm LUCKE, Hideshi TAMARU, Yaeko FUJITA	Name: SONY CORPORA 7-35 Kitashinagawa-Ku, Tokyo 1	wa 6-chome
Additional name(s) of conveying party(ies) attached? Yes <u>X</u> No	? Additional name(s) & address(es) a	
3. Nature of conveyance:		
X Assignment		
Security Agreement Merger		
Change of Name Other		
Execution Date(s): March 9, March 12, March 12, March 12 March 18 and March 12, 2001	2,	and the second s
/ Audication number(a) or natest number(a)	1	representative and a series of the series of
4. Application number(s) or patent number(s): If this document is being filed together the application is:	er with a new application, the execution da	ate of
A. Patent Application No.(s) <u>09/749,360</u> filed <u>D</u>	ecember 27, 2000	
Additional number	rs attached? <u> </u>	
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications a patents involved	and1_
Name: WILLIAM S. FROMMER	7. Total fee (37 CFR 3.41)	\$ 40.00
Internal Address: FROMMER LAWRENCE & HAUG LLP	X Enclosed Authorized to be	e charged to
Street Address: 745 FIFTH AVENUE	deposit account	50-0320
City: <u>NEW YORK</u> State: N.Y. Zip: 10151	Deposit account number: (Attach duplicate copy of this pag account)	e if paying by deposit
Do n	not use this space	
 Statement and signature. To the best of my knowledge and belief, the foregoin copy of the original document. 	ng information is true and correct and any a	attached copy is a true
GLENN F. SAVIT	LF LA	April 11, 2001
Name of Person Signing		Date of pages including cover nments, and document: 3
Do not	detach this portion	
	d with required cover sheet information to:	
Commissioner	of Patents and Trademarks	
∦ 8	Box Assignments ington, D.C. 20231	
Public burden reporting for this sample cover sheet is endeduning time for reviewing the document and gathering Send comments regarding this burden estimate to the U.S. PK2-1000C, Washington, D.C. 20231, and to the Office of Washington, D.C. 20503.	the data needed, and completing and review Patent and Trademark Office, Office of In-	ing the sample cover sheet. formation Systems,

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

INFORMATION PROCESSING DEVICE. INFORMATION PROCESSING METHOD AND STORAGE MEDIUM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo 141, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: $\underline{09/749,360}$, Filing Date: $\underline{December\ 27,\ 2000}$.

This assignment executed on the dates indicated below.

Junichi YAMASHITA	
Name of first or sole inventor	Execution date of U.S. Patent Application
Saitama, Japan	
Residence of first or sole inventor Junichi Yamashita	March 9, 2001
Signature of first or sole inventor	Date of this assignment
Hiroaki OGAWA	
Name of second inventor	Execution date of U.S. Patent Application
Chiba, Japan	
Residence of second inventor	March 12, 2001
Signature of second inventor	Date of this assignment
Hitoshi HONDA	
Name of third inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of third inventor	march 12,200/
Signature of third inventor	Date of this assignment

PATENT Page 1 of 2

ADDITIONAL INVENTORS

Hermut Lucke		
Name of fourth inventor	Execution date of U.S. Patent Application	
Tokyo, Japan		
Residence of fourth inventor **M fuche**	March 12, 2001	
Signature of fourth inventor	Date of this assignment	
Hideshi TAMARU		
Name of fifth inventor	Execution date of U.S. Patent Application	
Kanagawa, Japan		
Residence of fifth inventor (didente Tamarice	March 18. 2001	
Signature of fifth inventor	Date of this assignment	
Yaeko FUJITA		
Name of sixth inventor	Execution date of U.S. Patent Application	
Tokyo, Japan		
Residence of sixth inventor	March 12, 200/	
Signature of sixth inventor	Date of this assignment	